

V_{DSS}	250V
$R_{DS(on)(Max.)}$	1.3Ω
I_D	±4.0A
P_D	29W

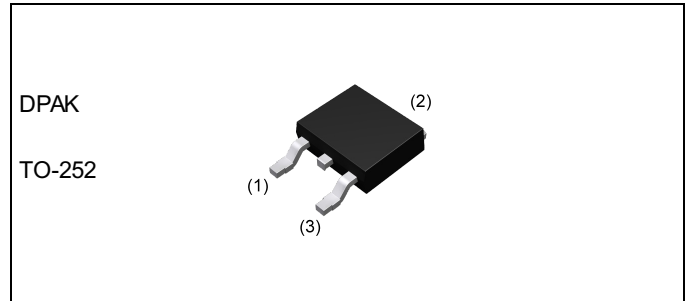
●Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Drive circuits can be simple
- 4) Pb-free plating ; RoHS compliant
- 5) AEC-Q101 Qualified

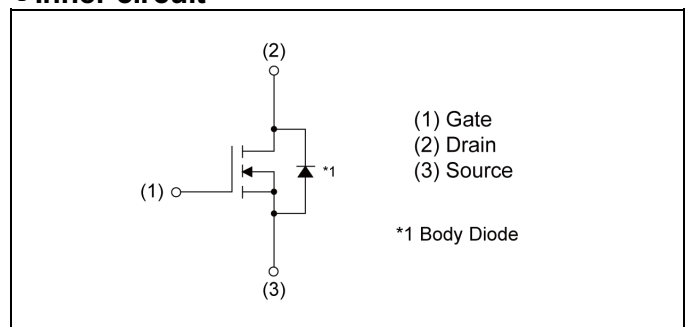
●Application

Switching Power Supply

●Outline



●Inner circuit



●Packaging specifications

Type	Packing	Embossed Tape
	Reel size (mm)	330
Tape width (mm)	16	
Quantity (pcs)	2500	
Taping code	TL	
Marking	RD3U041AA	

●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	250	V
Continuous drain current ($T_c = 25^\circ\text{C}$)	I_D^{*1}	±4.0	A
Pulsed drain current	I_{DP}^{*2}	±16	A
Gate - Source voltage	V_{GSS}	±30	V
Avalanche current, single pulse	I_{AS}^{*3}	2.0	A
Avalanche energy, single pulse	E_{AS}^{*3}	1.61	mJ
Power dissipation ($T_c = 25^\circ\text{C}$)	P_D^{*4}	29	W
Junction temperature	T_j	150	°C
Operating junction and storage temperature range	T_{stg}	-55 to +150	°C

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}^{*4}	-	-	4.3	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*5}	-	-	100	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	250	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 250V, V_{GS} = 0V$	-	-	10	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_D = 1mA$	3.5	-	5.5	V
Static drain - source on - state resistance	$R_{DS(on)}^{*6}$	$V_{GS} = 10V, I_D = 2.0A$	-	0.93	1.3	Ω
Gate resistance	R_G	$f = 1MHz, \text{open drain}$	-	4.0	-	Ω

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	350	-	pF
Output capacitance	C_{oss}	$V_{DS} = 25V$	-	30	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	15	-	
Turn - on delay time	$t_{d(on)}^{*6}$	$V_{DD} \approx 125V, V_{GS} = 10V$	-	15	-	ns
Rise time	t_r^{*6}	$I_D = 2.0A$	-	14	-	
Turn - off delay time	$t_{d(off)}^{*6}$	$R_L \approx 62\Omega$	-	18	-	
Fall time	t_f^{*6}	$R_G = 10\Omega$	-	15	-	

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*6}	$V_{DD} \approx 125V$	-	8.5	-	nC
Gate - Source charge	Q_{gs}^{*6}	$I_D = 4.0A$	-	3.5	-	
Gate - Drain charge	Q_{gd}^{*6}	$V_{GS} = 10V$	-	3.5	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \approx 125V, I_D = 4.0A$	-	7.8	-	V

*1 Limited only by maximum temperature allowed.

*2 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 $L \approx 500\mu\text{H}$, $V_{DD} = 50V$, $R_G = 25\Omega$, starting $T_j = 25^\circ\text{C}$ Fig.3-1,3-2

*4 $T_c = 25^\circ\text{C}$

*5 Mounted on an epoxy PCB FR4 (20×20×0.8mm)

*6 Pulsed

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Source current	I_S^{*1}	$T_C = 25^\circ\text{C}$	-	-	4.0	A
Pulsed source current	I_{SP}^{*2}		-	-	16	A
Source-Drain voltage	V_{SD}^{*6}	$V_{GS} = 0\text{V}, I_S = 4.0\text{A}$	-	-	1.5	V
Reverse recovery time	t_{rr}^{*6}	$I_S = 4.0\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	95	-	ns
Reverse recovery charge	Q_{rr}^{*6}		-	0.3	-	μC
Peak reverse recovery current	I_{rr}^{*6}		-	6.3	-	A

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

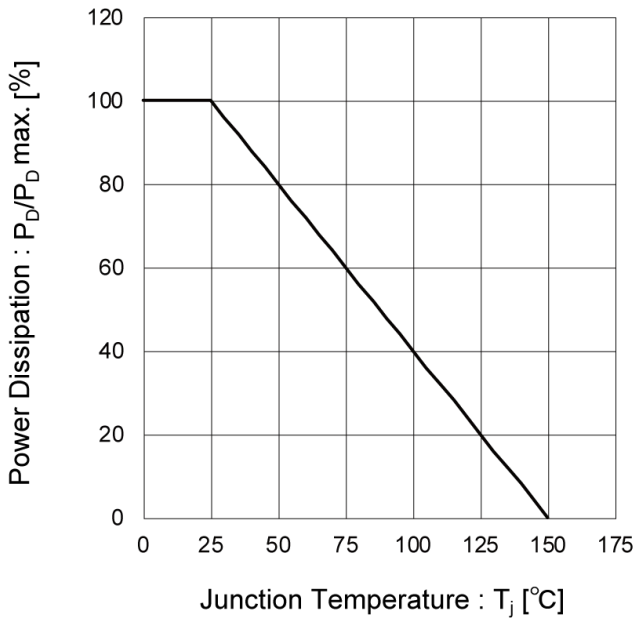


Fig.2 Drain Current Derating Curve

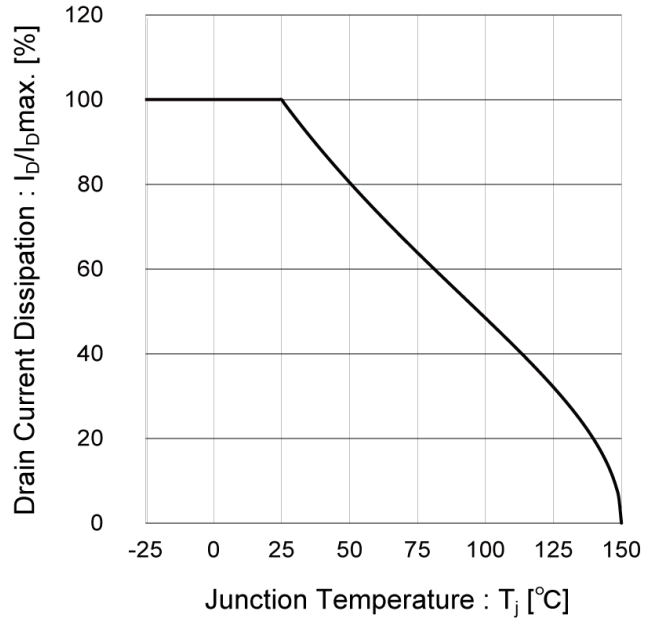


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

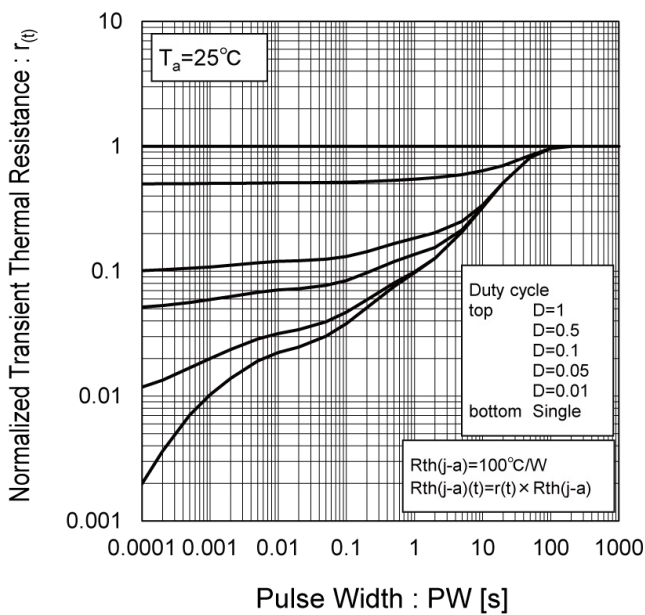
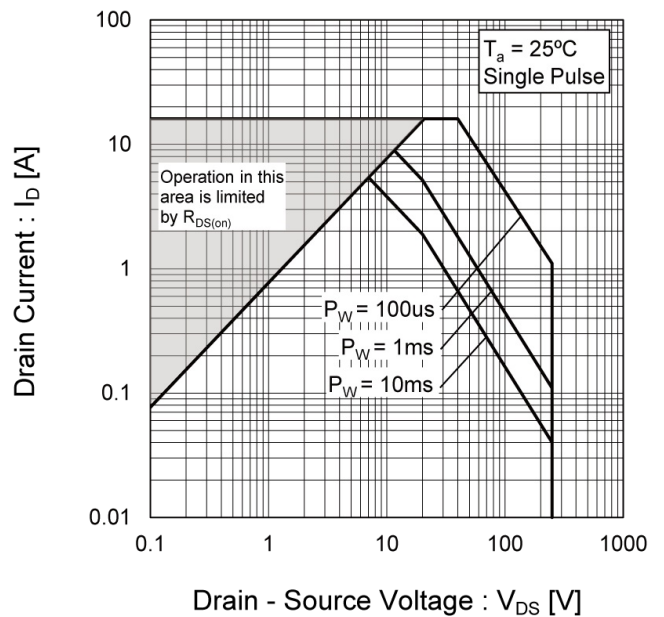


Fig.4 Maximum Safe Operating Area



●Electrical characteristic curves

Fig.5 Avalanche Energy Derating Curve

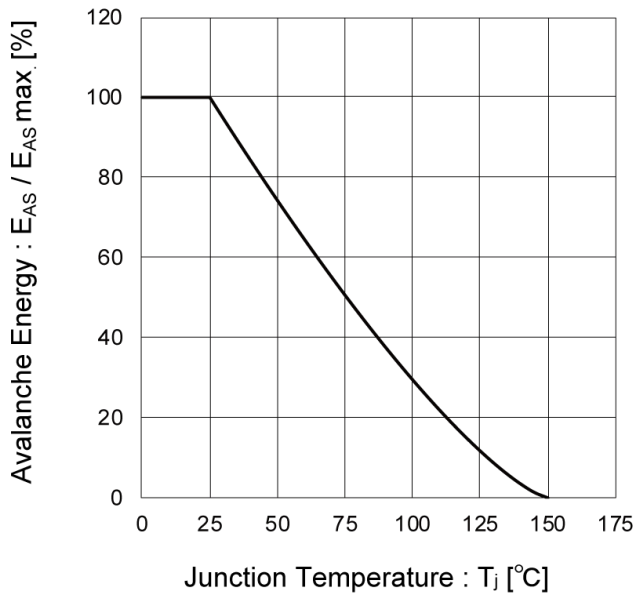


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

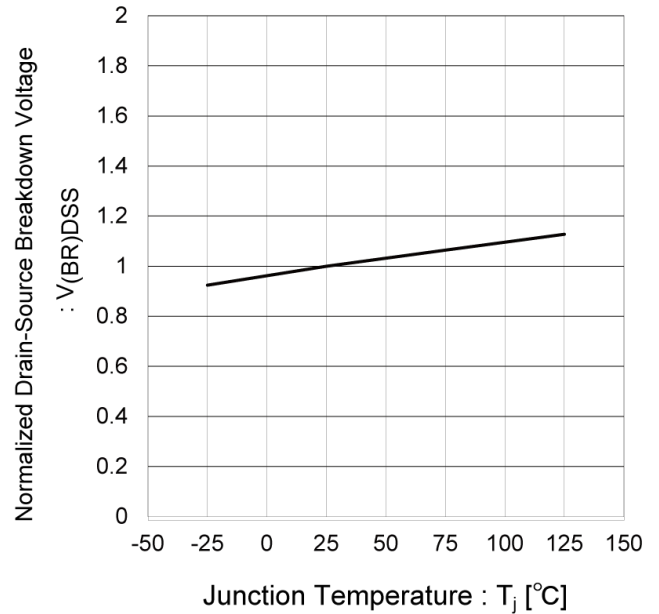


Fig.7 Output Characteristics(I)

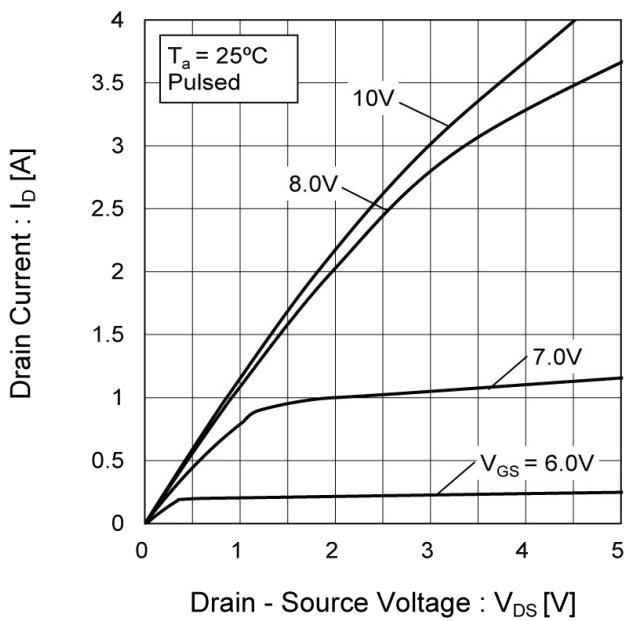
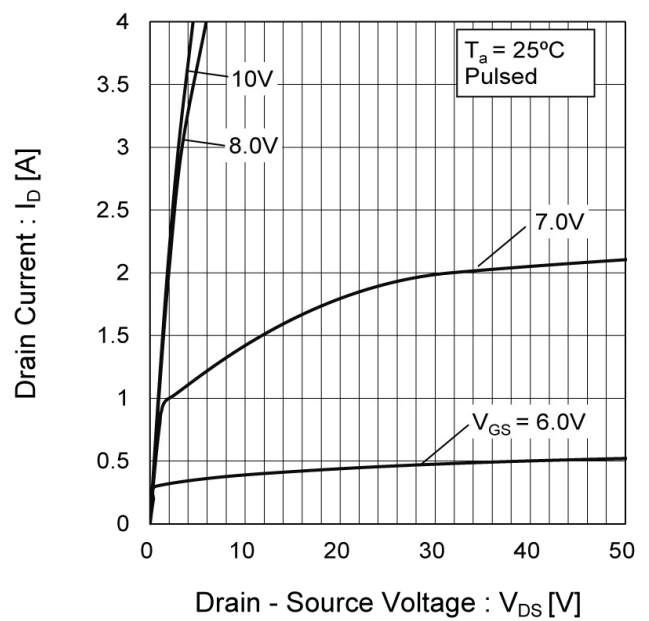


Fig.8 Output Characteristics(II)



● Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Drain Current

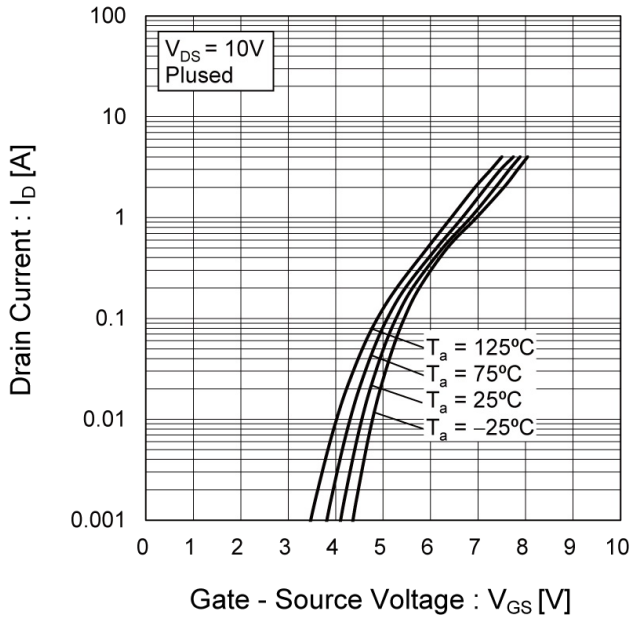


Fig.10 Normalized Gate Threshold Voltage vs Junction Temperature

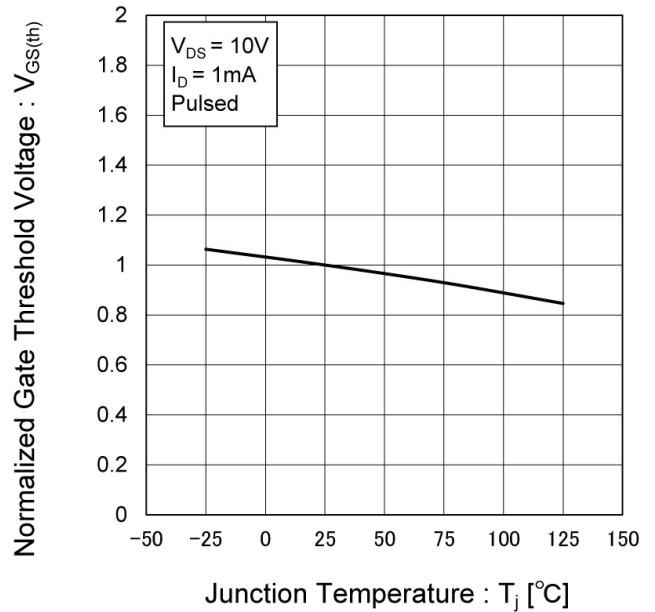


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

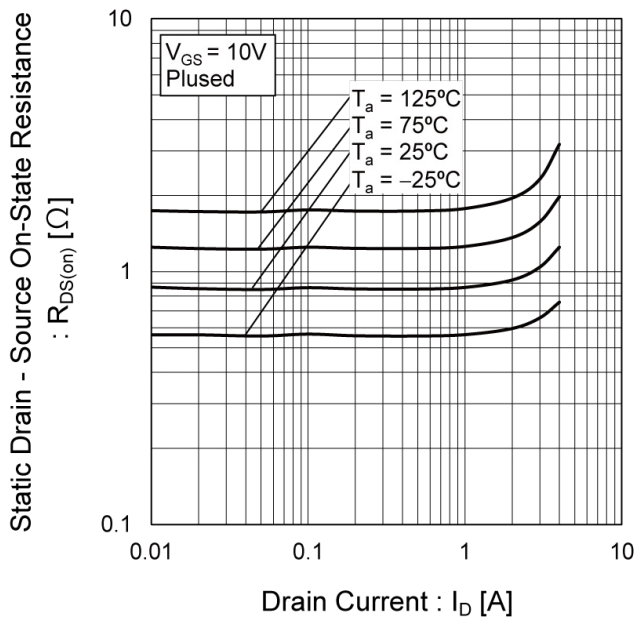
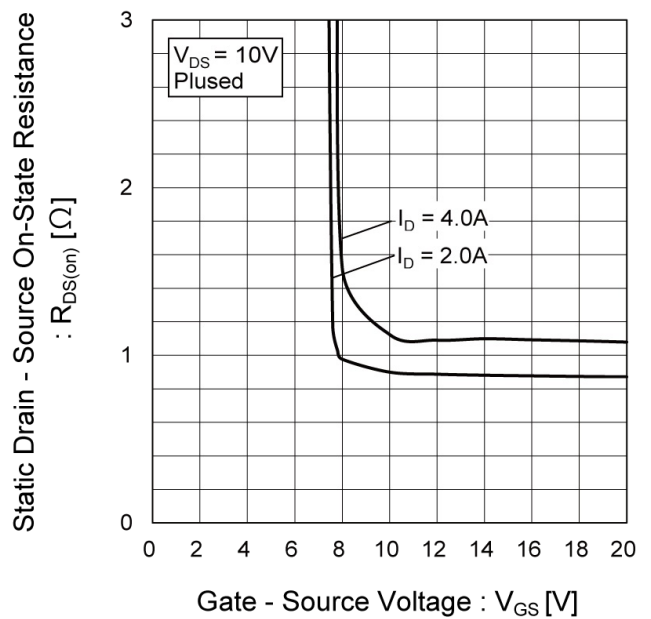


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

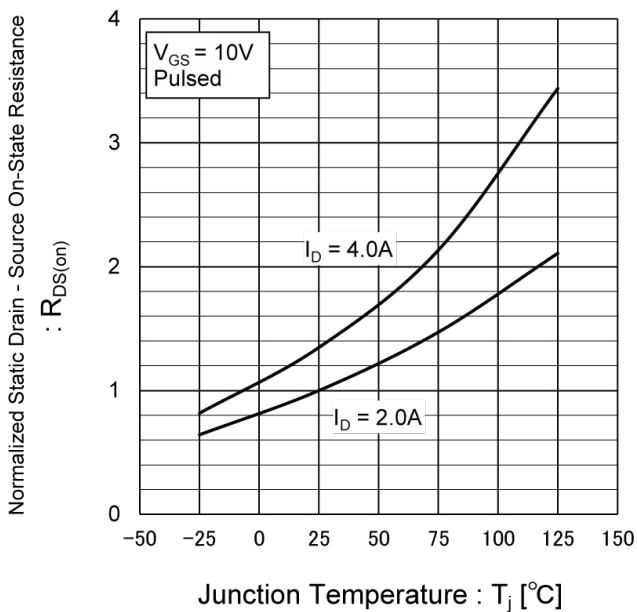


Fig.14 Capacitances

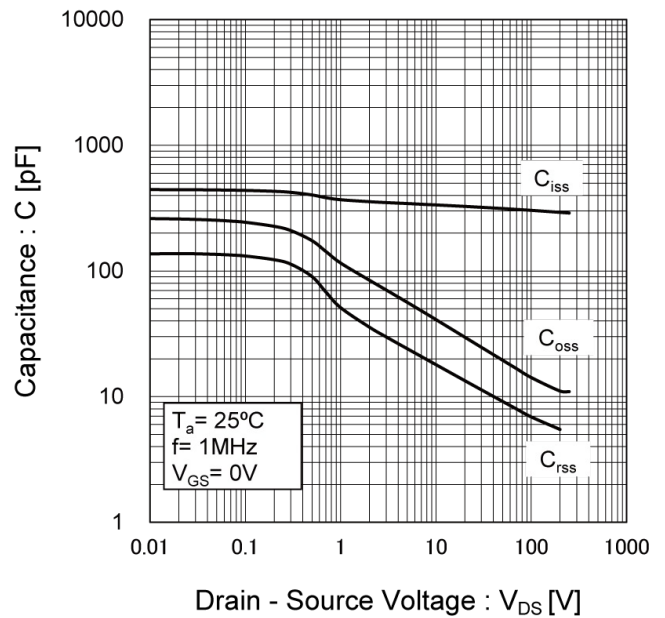


Fig.15 Switching Times

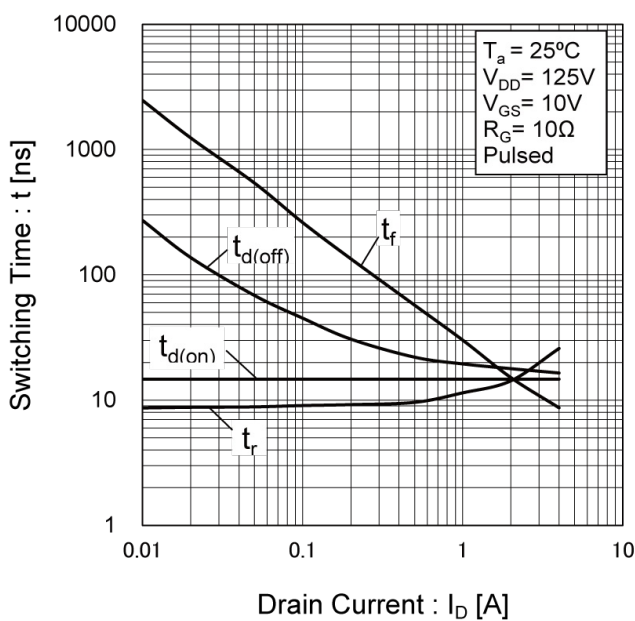
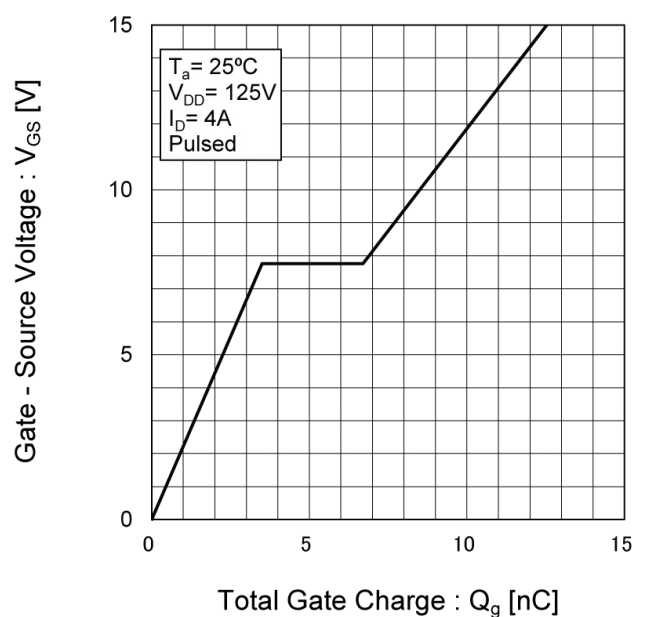


Fig.16 Gate Charge



● Electrical characteristic curves

Fig.17 Source Current vs. Source - Drain Voltage

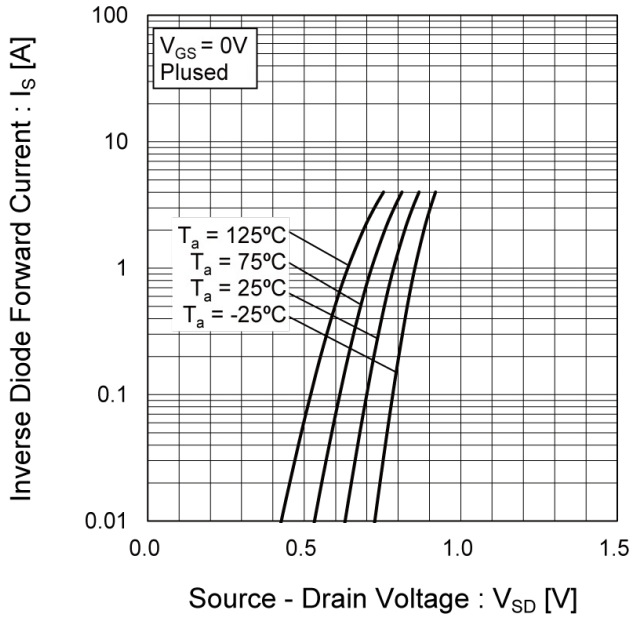
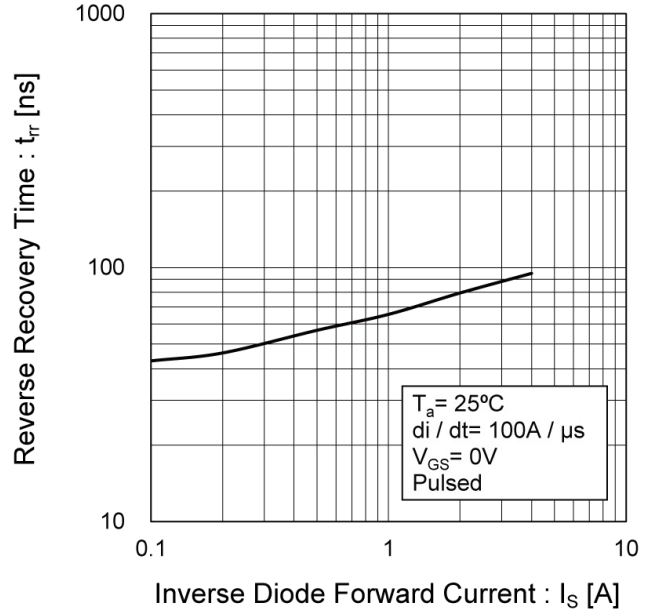


Fig.18 Reverse Recovery Time vs. Source Current



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

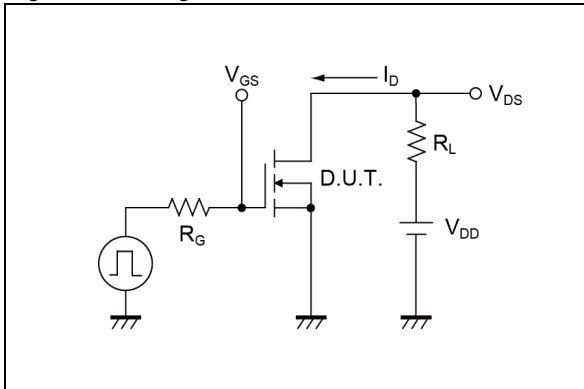


Fig.1-2 Switching Waveforms

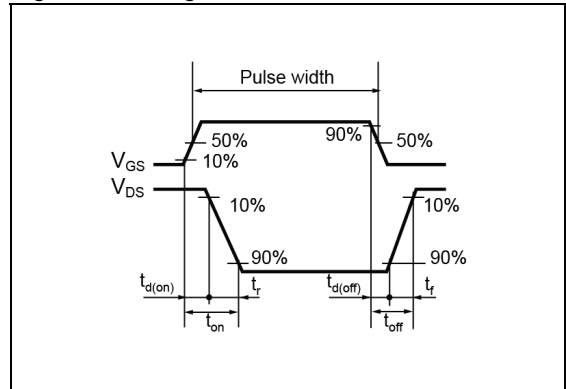


Fig.2-1 Gate Charge Measurement Circuit

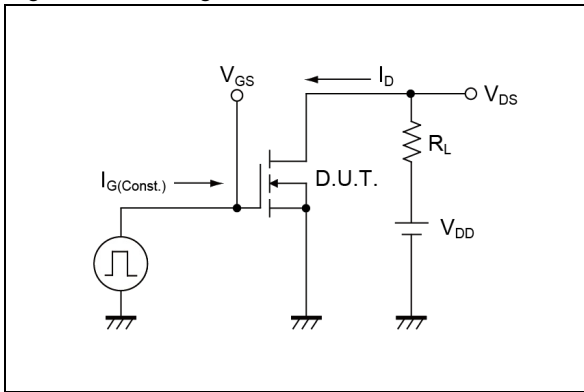


Fig.2-2 Gate Charge Waveform

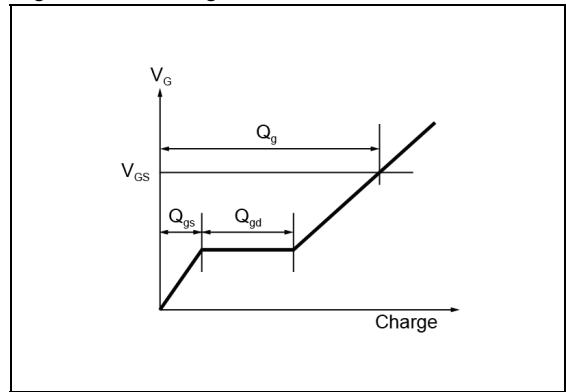


Fig.3-1 Avalanche Measurement Circuit

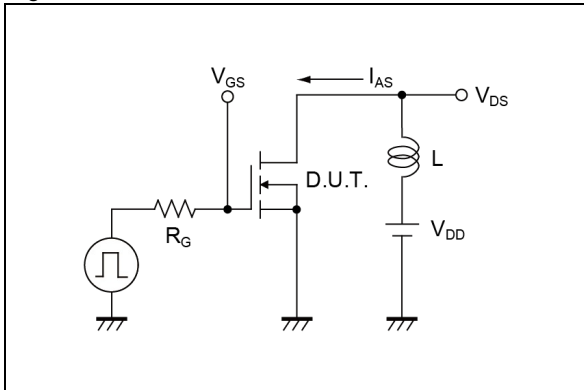


Fig.3-2 Avalanche Waveform

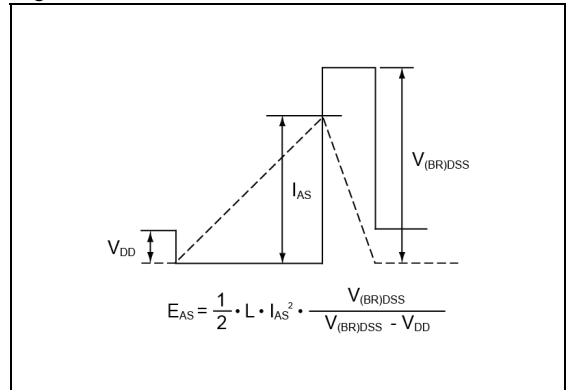


Fig.4-1 trr Measurement Circuit

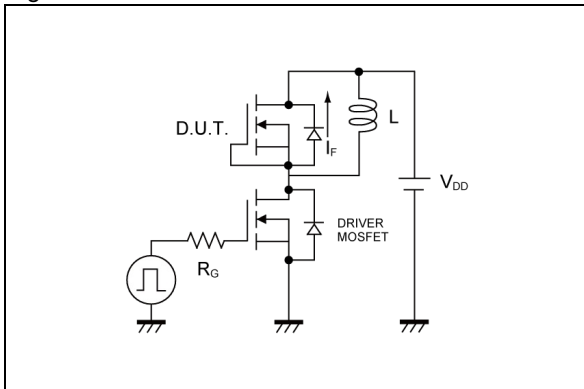
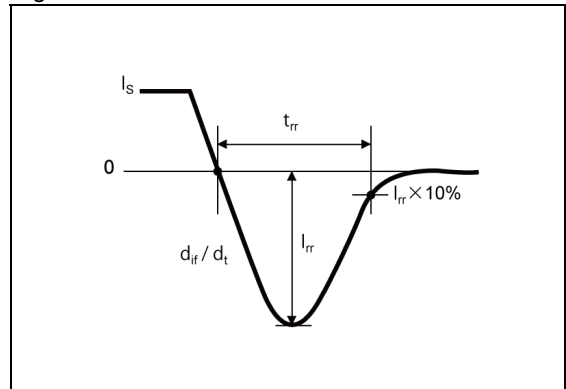
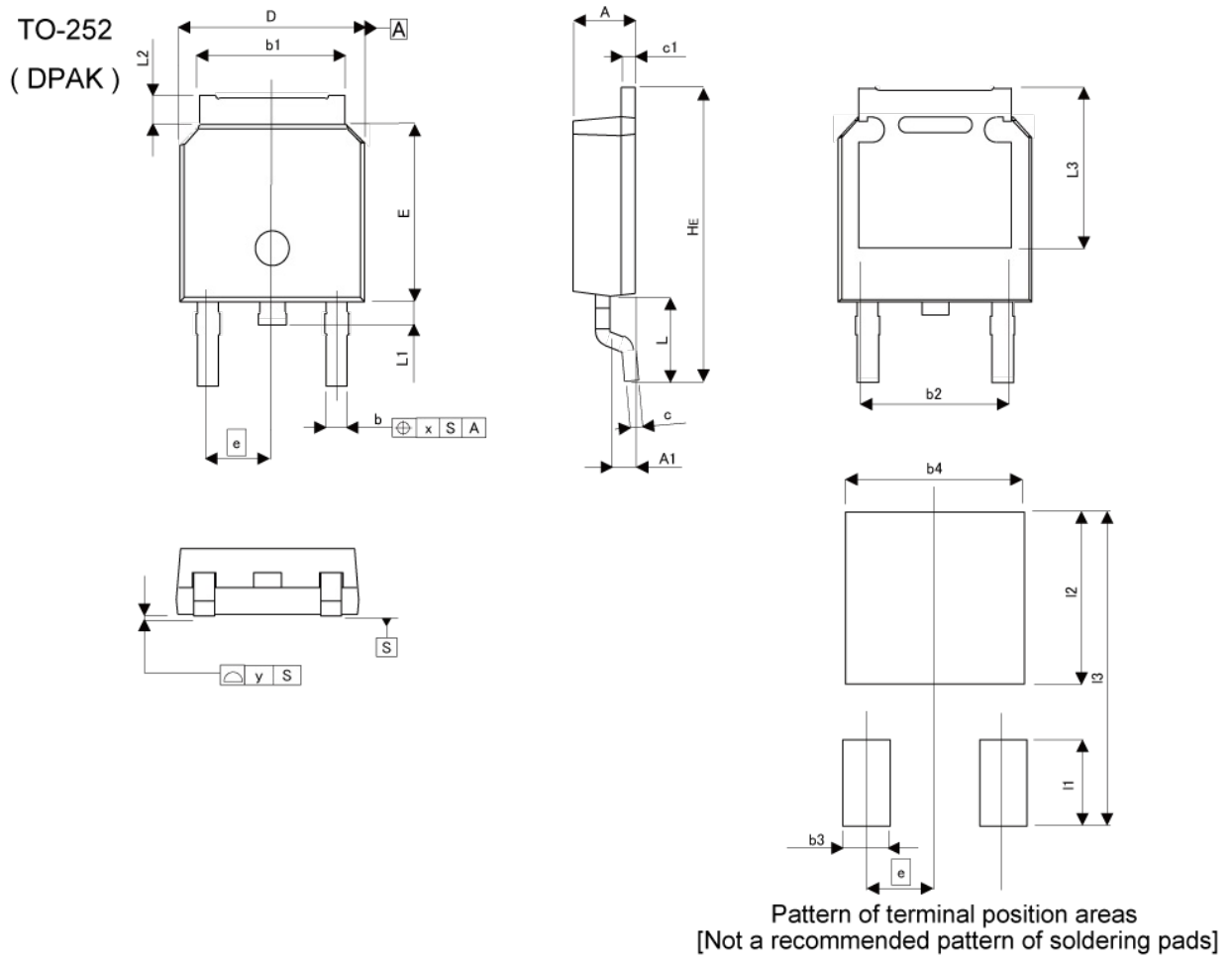


Fig.4-2 trr Waveform



●Dimensions



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.10		0.201	
c	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
e	2.30		0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.90		0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.30		0.209	
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b3	-	1.10	-	0.043
b4	-	5.40	-	0.213
l1	-	2.90	-	0.114
l2	-	5.50	-	0.217
l3	-	10.50	-	0.413

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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8. Confirm that operation temperature is within the specified range described in the product specification.
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2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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